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(54) **TRANSPARENT FILM AND MANUFACTURING METHOD THEREFOR**

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(57) **ABSTRACT**

A transparent film including: a transparent substrate; and a conducting fiber-containing layer that is stacked on at least one main surface of the transparent substrate material and contains conducting fibers substantially evenly dispersed in a plane view and a binder resin. The transparent film has a high resistance part in which an undercoat layer is provided between the transparent substrate material and the conducting fiber-containing layer, and a low resistance part in which the undercoat layer is not provided between the transparent substrate material and the conducting fiber-containing layer. The relationship between a sheet resistance value R_H of the high resistance part and a sheet resistance value R_L of the low resistance part is expressed as $R_H/R_L>100$. The undercoat layer contains a resin having at least one group or boding part having (—NH—).